US00D539640S

(12) United States Design Patent

Liu et al.

(10) **Patent No.: US D539,640 S**

(45) **Date of Patent: ** Apr. 3, 2007**

---

(54) **CPU HEAT SINK PACKAGING BOX**

(75) Inventors: **Ming-Fang Liu**, Shenzhen (CN); **Chun-Chi Liang**, Tu-Chen (TW); **Yun-Dong Xu**, Shenzhen (CN)

(73) Assignee: **Hon Hai Precision Ind. Co., Ltd**, Taipei Hsien (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/216,168**

(22) Filed: **Oct. 28, 2004**

(30) **Foreign Application Priority Data**

Jul. 17, 2004 (CN) 200430062949

(51) **LOC (8) Cl.** **09-03**

(52) **U.S. Cl.** **D9/415**

(58) **Field of Classification Search** D9/415, D9/414, 418, 430; 206/461, 462, 463, 464, 206/465, 471, 485, 486–488

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D206,771 S	*	1/1967	Valiulis	D9/415
D257,226 S	*	10/1980	Kimball	D9/415
D270,617 S	*	9/1983	Skowronski et al.	D9/415
4,742,914 A	*	5/1988	Klein	206/461
D429,637 S	*	8/2000	Kumakura et al.	D9/415

* cited by examiner

Primary Examiner—Stella Reid
Assistant Examiner—Derrick Holland
(74) *Attorney, Agent, or Firm*—Wei Te Chung

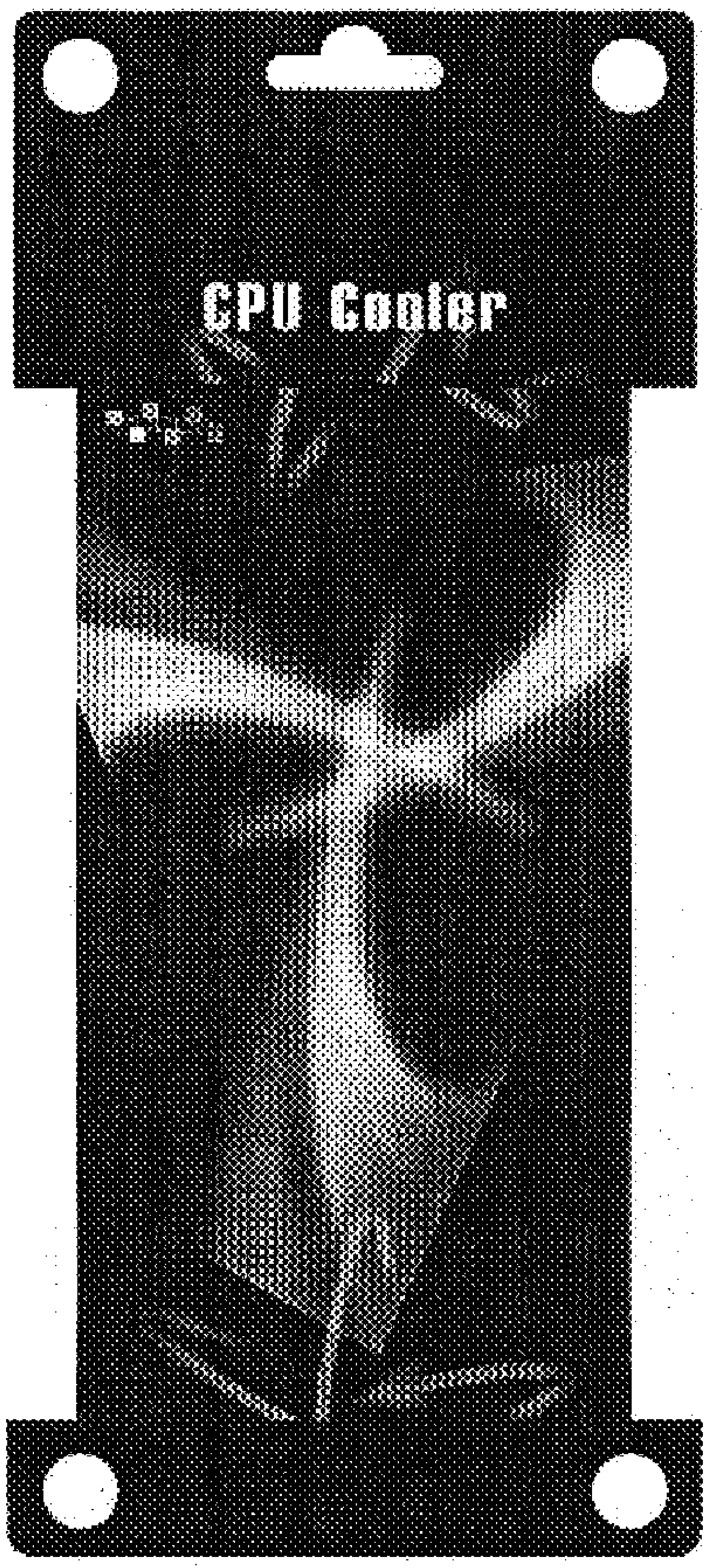
(57) CLAIM

The ornamental design for a CPU heat sink packaging box, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of a CPU heat sink packaging box showing our new design, in disassembled condition;
FIG. **2** is a top plan view thereof, in assembled condition;
FIG. **3** is a side elevational view thereof;
FIG. **4** is a side elevational view thereof from the side opposite that shown in FIG. **3**;
FIG. **5** is an end elevational view thereof; and,
FIG. **6** is an end elevational view thereof from the end opposite that shown in FIG. **5**.
The black shading in the drawing is intended to represent the color black in the claimed design.

1 Claim, 4 Drawing Sheets



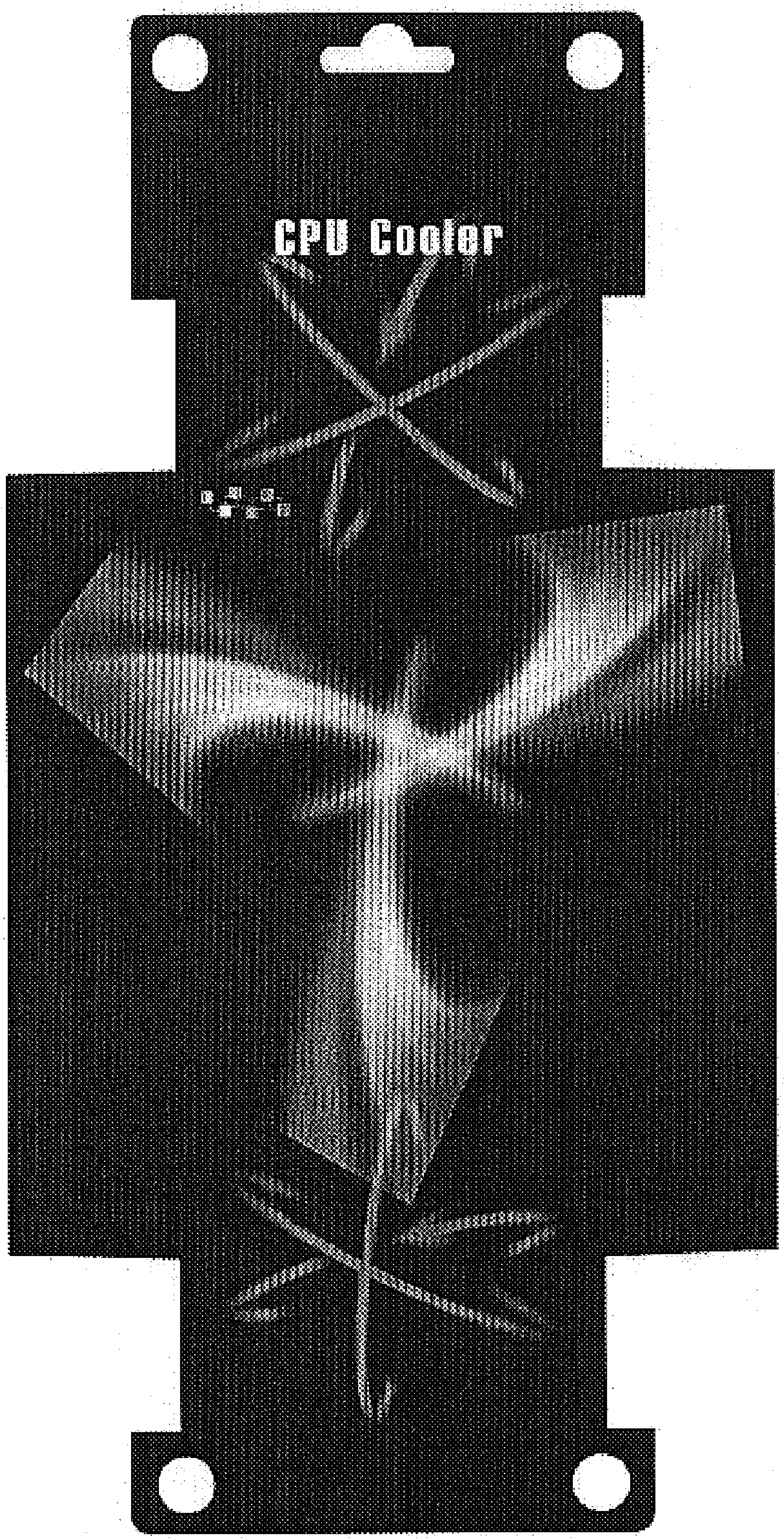


FIG. 1

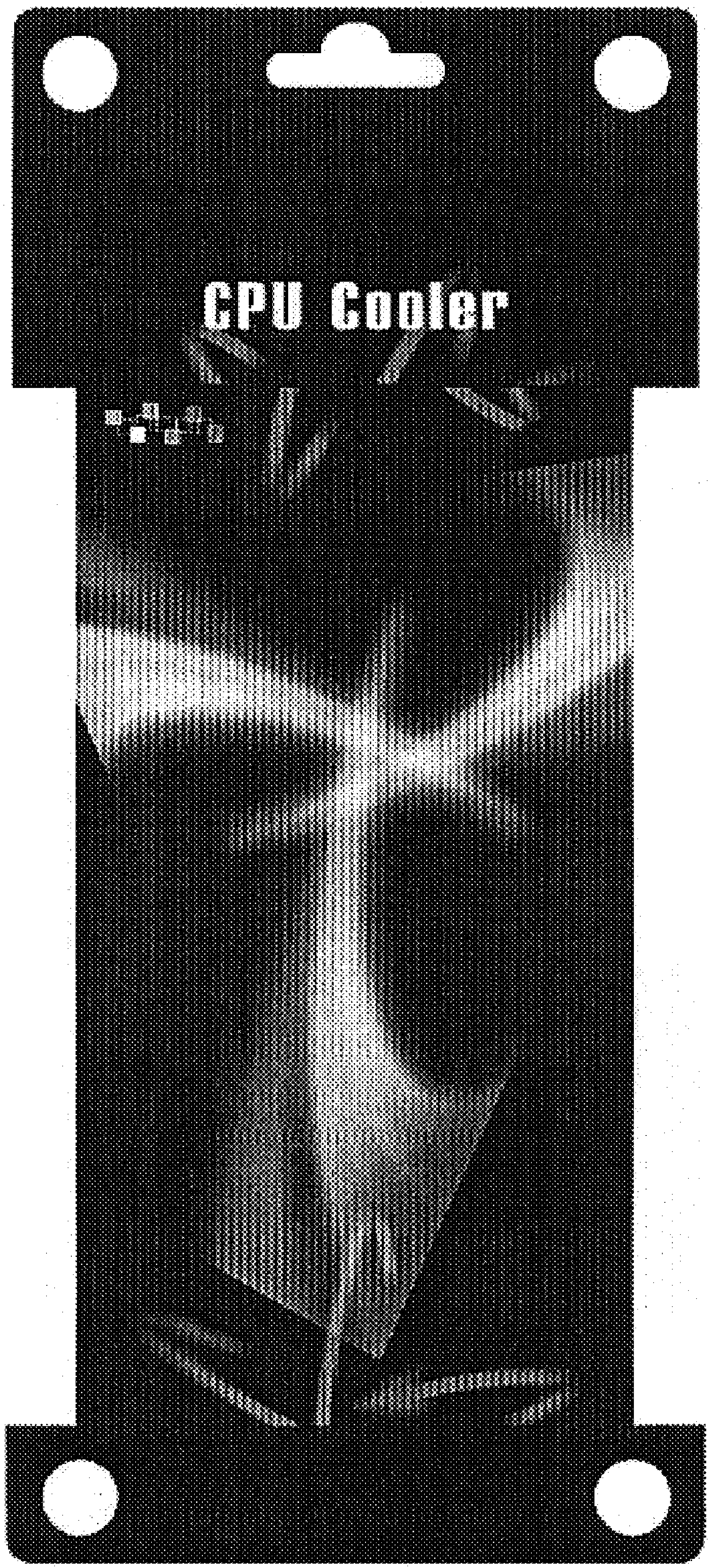


FIG. 2

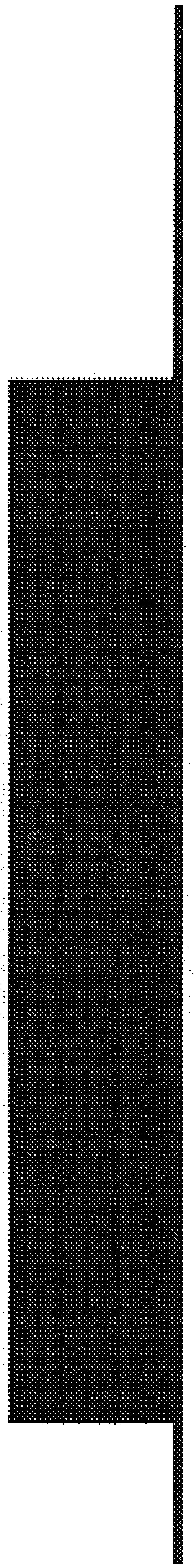


FIG. 3

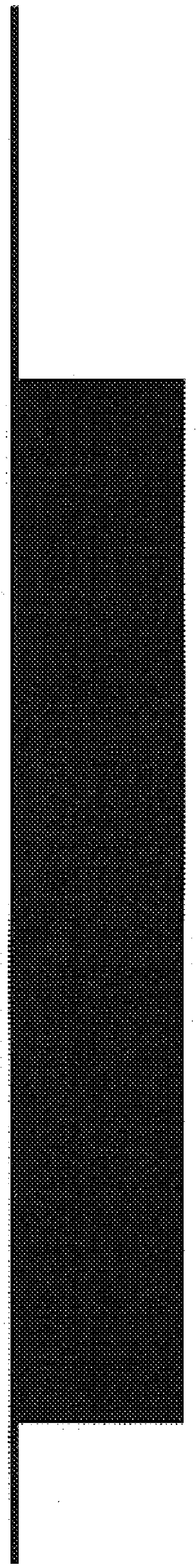


FIG. 4

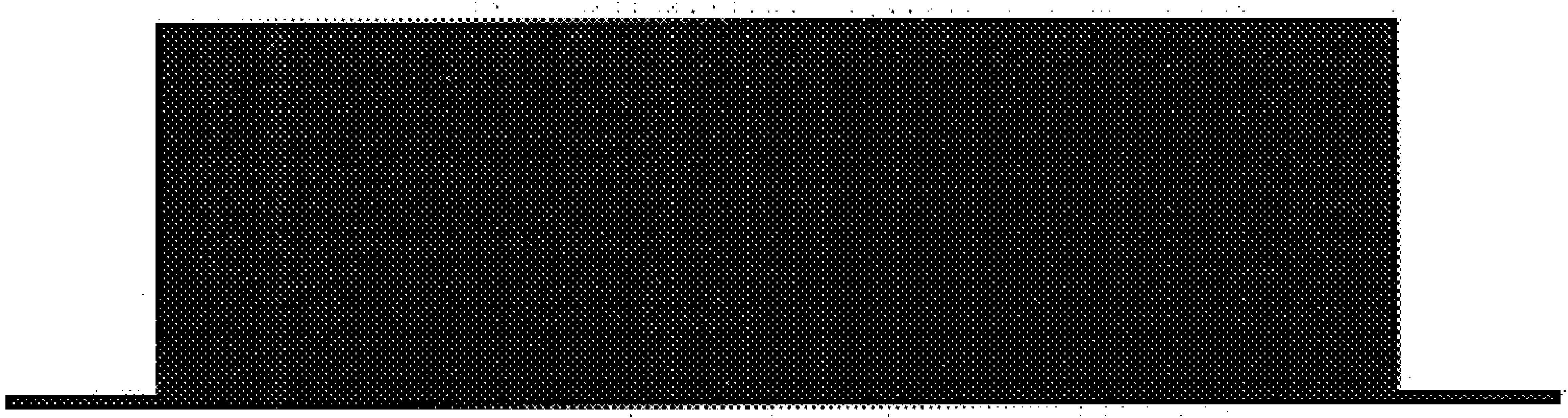


FIG. 5

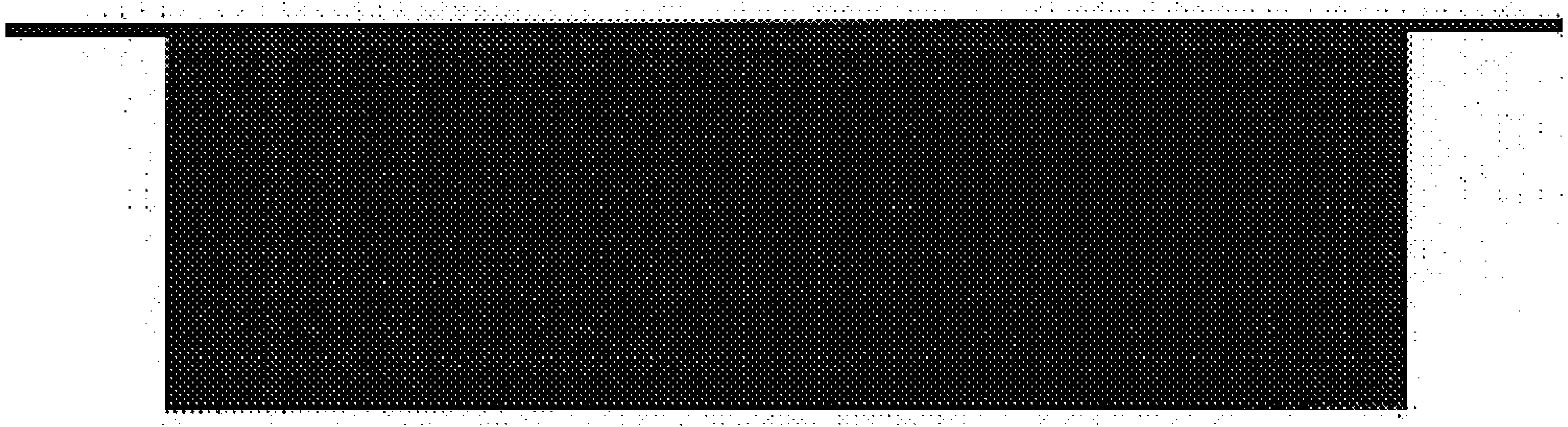


FIG. 6